Thermal paste GD-3, 0.5g, 7.5 W/m K

Reference: AM0422
EAN13: -
HS code: 38249996

Product attributes:

Product features:

Color: Gray
Max. operating temperature: 120 °C
Thermal conductivity: 7.5 W/mK

Product description:

Thermally conductive paste GD-3 is designed to improve thermal contact between the component and the heat sink. It is used during the assembly or maintenance of processors, LED elements, GPUs and other electronic components where heat transfer from the surface of the component to the heat sink is required.

Technical specifications

- Product type: thermal paste
- Designation: GD-3
- Color: gray
- Refill weight: 0.5 g
- Thermal conductivity: 7.5 W/m K
- Specific gravity: 2.5 g/cc
- Operating temperature: -35 to +120 °C

Functions and features

- The paste fills microscopic irregularities between the mating surfaces.
- It helps transfer heat more efficiently between the electronic component and the heat sink.
- Suitable for use on processors, graphics chips and LED modules with heatsink.

Ideal for

- Installation and service of processor coolers
- Applications on GPUs and other high-performance semiconductor devices
- LED lighting with heat dissipation via a heat sink
- Electronic assemblies requiring thermal contact between the component and the heat sink

Package contents

- 1x thermal paste GD-3 0.5 g

Why choose this product?

- It is a functional material designed for heat transfer between the component and the heat sink.
- The technical specifications for processors, GPUs and LEDs meet common heat dissipation requirements in electronics.

Installation and operating instructions

- Before application, clean the contact surfaces from old paste, dirt and grease.
- Apply only a thin layer to the area intended for heat transfer.
- After application, ensure proper and even pressure on the radiator.
- Avoid contaminating the paste with dust and dirt.

Safety notice

- The product is intended for use in electronic devices; incorrect application may impair heat dissipation and lead to overheating of components.
- Do not apply to electrical contacts, connectors or other conductive parts of the wiring unless specifically designated by the design of the device.
- Use only on a disconnected and cooled device.
- Assemble electronic components taking into account the requirements of the specific device and the risk of damage if assembled incorrectly.